

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	14
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	5.84 E-01	87.7	877000	59.44		594361
Thermosets	Epoxy Resin	Proprietary	3.33 E-02	5.0	50000	3.39		33886
Thermosets	Phenol Resin	Proprietary	3.33 E-02	5.0	50000	3.39		33886
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.33 E-02	2.0	20000	1.36		13554
Other inorganic materials	Carbon Black	1333-86-3	2.00 E-03	0.3	3000	0.20		2033
Subtotal			6.66 E-01	100	1000000	67.77		677721

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.82 E-01	97.50	975000	28.74		287363
Copper & its alloys	Iron	7439-89-6	6.81 E-03	2.35	23500	0.69		6926
Copper & its alloys	Zinc	7440-66-6	3.48 E-04	0.12	1200	0.04		354
Copper & its alloys	Phosphorus	7723-14-0	8.69 E-05	0.03	300	0.01		89
Subtotal			2.90 E-01	100.00	1000000	29.47		294732

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.93 E-03	100.0	1000000	0.30		2977

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.01 E-02	100.0	1000000	2.05		20459

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	6.40 E-04	99.99	1000000	0.07		651

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.50 E-03	100.0	1000000	0.25		2544

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.20 E-04	80	800000	0.07		733
Thermosets	Epoxy Resin	Proprietary	1.35 E-04	15	150000	0.01		137
Others	Curing agent & hardener	Proprietary	4.50 E-05	5	50000	0.00		46
Subtotal			9.00 E-04	100	1000000	0.09		916

Package Totals				Weight (g)	Percentage (%)	PPM
				9.83 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	14
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
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				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	5.84 E-01	87.7	877000	59.44		594361
Thermosets	Epoxy Resin	Proprietary	3.33 E-02	5.0	50000	3.39		33886
Thermosets	Phenol Resin	Proprietary	3.33 E-02	5.0	50000	3.39		33886
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.33 E-02	2.0	20000	1.36		13554
Other inorganic materials	Carbon Black	1333-86-3	2.00 E-03	0.3	3000	0.20		2033
Subtotal			6.66 E-01	100	1000000	67.77		677721

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Copper & its alloys	Iron	7439-89-6	6.81 E-03	2.35	23500	0.69		6926
Copper & its alloys	Zinc	7440-66-6	3.48 E-04	0.12	1200	0.04		354
Copper & its alloys	Phosphorus	7723-14-0	8.69 E-05	0.03	300	0.01		89
Subtotal			2.90 E-01	100.00	1000000	29.47		294732

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Precious metals	Silver	7440-22-4	2.93 E-03	100.0	1000000	0.30		2977

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.71 E-02	85.0	850000	1.74		17390
Tin & its alloys	Lead	7439-92-1	3.02 E-03	15.0	150000	0.31		3069
Subtotal			2.01 E-02	100.0	1000000	2.05		20459

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	6.40 E-04	99.99	1000000	0.07		651

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